

NCE N-Channel Enhancement Mode Power MOSFET

Description

The NCE3010S uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications.

General Features

V_{DS} =30V,I_D =10A

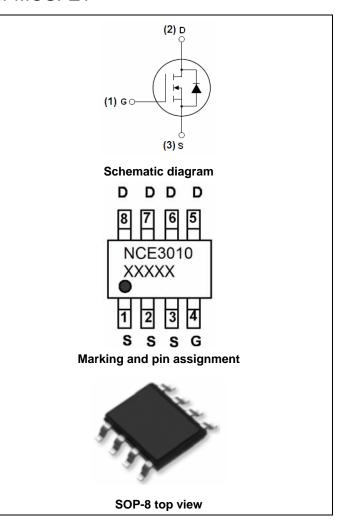
 $R_{DS(ON)} < 12m\Omega @ V_{GS} = 10V$

 $R_{DS(ON)}$ <16m Ω @ V_{GS} =4.5V

- High density cell design for ultra low Rdson
- Fully characterized Avalanche voltage and current

Application

- Power switching application
- Hard Switched and High Frequency Circuits
- Uninterruptible Power Supply



Package Marking and Ordering Information

	<u> </u>				
Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
NCE3010	NCE3010S	SOP-8	Ø330mm	12mm	2500 units

Absolute Maximum Ratings (T_A=25 ℃unless otherwise noted)

U 1 11	,		
Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V _{DS}	30	V
Gate-Source Voltage	V _G S	±20	V
Drain Current-Continuous	I _D	10	А
Drain Current-Continuous(T _C =100 °C)	I _D (100℃)	6	Α
Pulsed Drain Current	I _{DM}	50	Α
Maximum Power Dissipation	P _D	2.5	W
Operating Junction and Storage Temperature Range	T_{J}, T_{STG}	-55 To 150	$^{\circ}$ C

Thermal Characteristic

Thermal Resistance, Junction-to-Case ^(Note 2)	$R_{ heta JC}$	50	°C/W



Electrical Characteristics (T_A=25 °C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	30	33	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =30V,V _{GS} =0V	-	-	1	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V,V _{DS} =0V	-	-	±100	nA
On Characteristics (Note 3)						
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} ,I _D =250μA	1	1.6	3	V
Drain-Source On-State Resistance	В	V _{GS} =10V, I _D =10A	-	8	3 12 1 16 	m0
Diain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =4.5V, I _D =5A	-	11	16	mΩ S PF PF
Forward Transconductance	g FS	V _{DS} =5V,I _D =10A	15	-	-	S
Dynamic Characteristics (Note4)			•			
Input Capacitance	C _{lss}	\/ -45\/\/ -0\/	-	1550	-	PF
Output Capacitance	Coss	V _{DS} =15V,V _{GS} =0V, F=1.0MHz	-	300	-	PF
Reverse Transfer Capacitance	C _{rss}	F=1.0IVID2	-	- 180 - I		PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	t _{d(on)}		-	30	-	nS
Turn-on Rise Time	t _r	V_{DD} =25 V , I_{D} =1 A	-	20	-	nS
Turn-Off Delay Time	t _{d(off)}	V_{GS} =10 V , R_{GEN} =6 Ω	-	100	-	nS
Turn-Off Fall Time	t _f		-	80	-	nS
Total Gate Charge	Qg	\/ -15\/ -100	-	13	-	nC
Gate-Source Charge	Q _{gs}	V_{DS} =15V, I_D =10A, V_{GS} =5V	-	5.5	-	nC
Gate-Drain Charge	Q_{gd}	v _{GS} –5v	-	3.5	-	nC
Drain-Source Diode Characteristics			-			-
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _S =10A	-	-	1.2	V
Diode Forward Current (Note 2)	I _S		-	-	10	Α

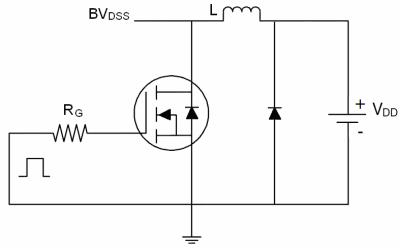
Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. Surface Mounted on FR4 Board, t ≤ 10 sec.
- 3. Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2%.
- 4. Guaranteed by design, not subject to production

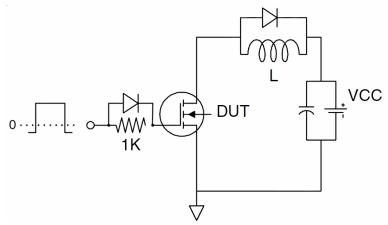


Test Circuit

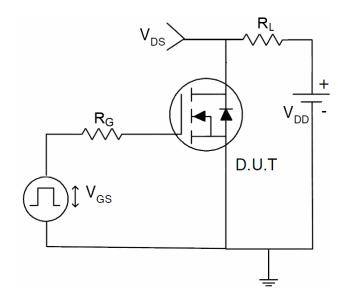
1) E_{AS} Test Circuits



2) Gate Charge Test Circuit:



3) Switch Time Test Circuit:





Typical Electrical and Thermal Characteristics (Curves)

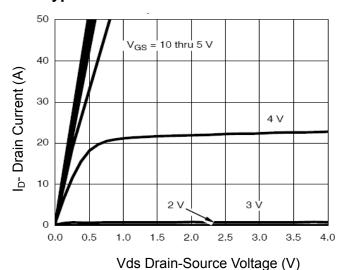
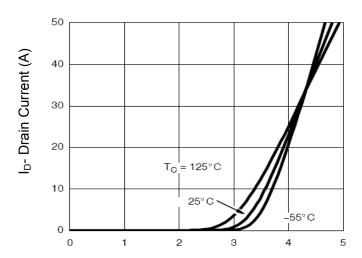


Figure 1 Output Characteristics



Vgs Gate-Source Voltage (V)
Figure 2 Transfer Characteristics

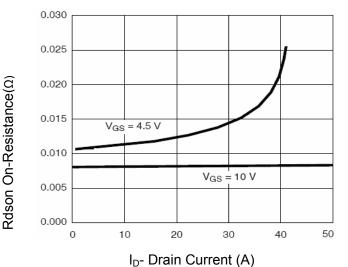


Figure 3 Rdson- Drain Current

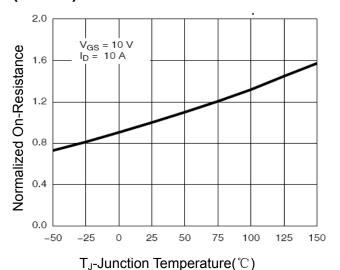


Figure 4 Rdson-JunctionTemperature

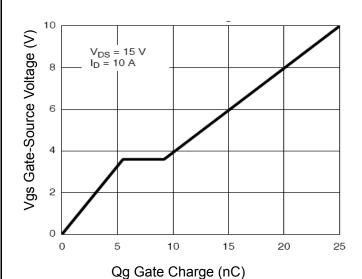


Figure 5 Gate Charge

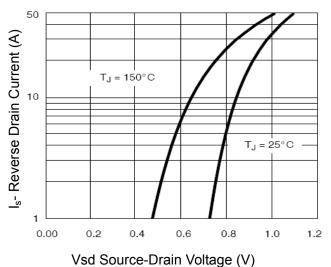


Figure 6 Source- Drain Diode Forward



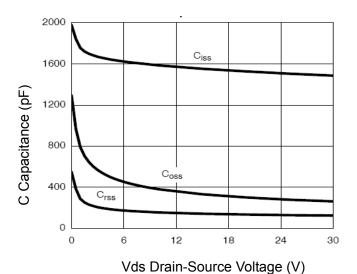
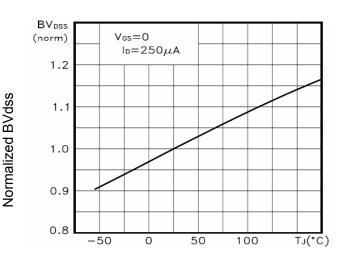
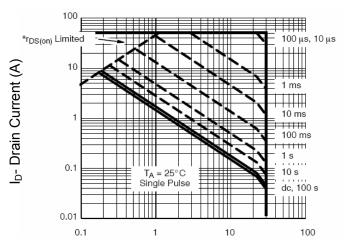


Figure 7 Capacitance vs Vds



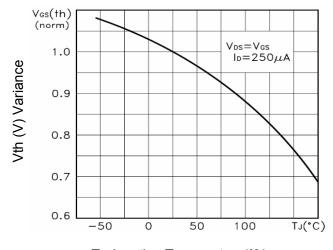
T_J-Junction Temperature(°C)

Figure 9 BV_{DSS} vs Junction Temperature



Vds Drain-Source Voltage (V)

Figure 8 Safe Operation Area



 T_J -Junction Temperature($^{\circ}$ C)

Figure 10 V_{GS(th)} vs Junction Temperature

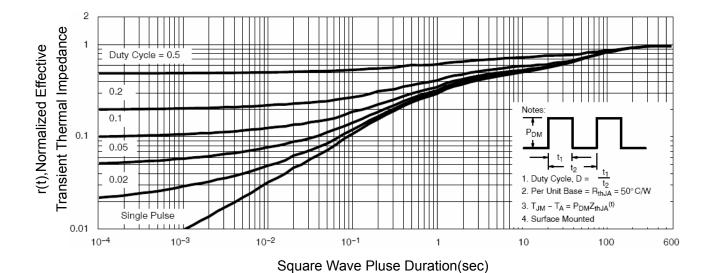
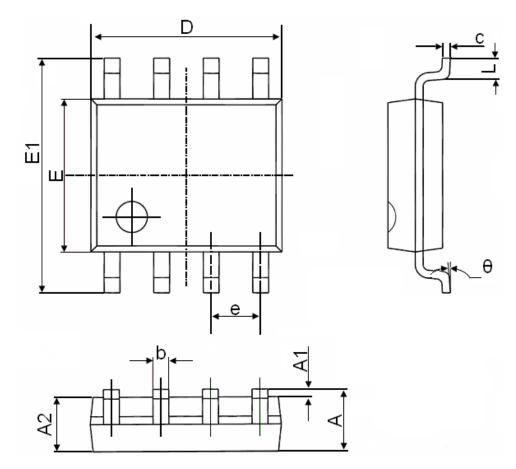


Figure 11 Normalized Maximum Transient Thermal Impedance



SOP-8 Package Information



Cumbal	Dimensions In Millimeters		Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
Α	1.350	1.750	0.053	0.069	
A1	0.100	0.250	0.004	0.010	
A2	1.350	1.550	0.053	0.061	
b	0.330	0.510	0.013	0.020	
С	0.170	0.250	0.006	0.010	
D	4.700	5.100	0.185	0.200	
Е	3.800	4.000	0.150	0.157	
E1	5.800	6.200	0.228	0.244	
е	1.270(BSC)		0.050	(BSC)	
L	0.400	1.270	0.016	0.050	
θ	0°	8°	0°	8°	

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